

METHOD OF MANUFACTURING ENHANCED FINISH SPUTTERING TARGETS

ABSTRACT

A method is provided for achieving an enhanced finish on a sputter target surface that results in good film uniformity, low particle counts, and little to no burn-in-time. The method involves chemically etching the surface of the sputter target by immersing the surface one or more times in an etching solution, with intermediate rinsing steps. The result is a surface substantially free of mechanical deformation that exhibits a surface similar to a sputtered target with a surface roughness of 10-30 μin .

